

## Reliability Results for Product Type PBSS4041SPN

Time period: Q1/2018 to Q4/2018

### Test Results

Test	Conditions	Duration	Quantity	Rejects
<b>TEST</b>				
# 1	Pre- and Post-Stress Electrical Test $T_{amb} = 25\text{ °C}$	N/A	all parts	see below
# 2	<b>PC</b> Preconditioning JESD22-A113 Bake $T_{amb} = 125\text{ °C}$ Soak $T_{amb} = 85\text{ °C}$ , RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	35200	0
# 5	<b>HTRB</b> High Temperature Reverse Bias MIL-STD-750-1 M1038 Method A $T_j = T_{jmax}$ , $V_r = 100\%$ of max. datasheet reverse voltage	1000 hours	9680	0
# 7	<b>TC</b> Temperature Cycling JESD22-A104 $-55\text{ °C}$ to $T_{jmax}$ , not to exceed $150\text{ °C}$	1000 cycles	8800	0
# 8	<b>AC</b> Autoclave JESD22-A102 $T_{amb} = 121\text{ °C}$ , RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	8800	0
# 9	<b>H3TRB</b> High Humidity High Temperature Reverse Bias JESD22-A101 $T_{amb} = 85\text{ °C}$ , RH = 85%, $V_r > 80\%$ of rated reverse voltage	1000 hours	8800	0
# 10	<b>IOL</b> Intermittent Operating Life MIL-STD-750 Method 1037 $t_{on} = t_{off}$ , devices powered to insure $\Delta T_j = 100\text{ °C}$ for 15000 cycles	1000 hours	8800	0
# 20	<b>RSH</b> Resistance to Solder Heat JESD22-A111 $260\text{ °C} \pm 5\text{ °C}$	10 s	2760	0
# 21	<b>SD</b> Solderability J-STD-002 Test method B and D		1950	0

### Calculation of FIT and MTBF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)

Confidence level 60%, derated to  $55\text{ °C}$ , activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate	MTBF
Nexperia DHAM	Small Signal Bipolar	9680	0	0.44 FIT	260034 years